

HLE-130-02-F-DV
HLE-110-02-L-DV
HLE-116-02-L-DV-K
HLE SERIES

(2,54 mm) .100"

COST-EFFECTIVE RELIABLE SOCKET

Mates With: TSW, MTSW, DW, EW, ZW, TLW, TSM, MTLW, HW SPECIFICATIONS For complete specifications and recommended PCB layouts A page bloom of the commended PCB layouts For complete specifications and recommended PCB layouts

see www.samtec.com?HLÉ
Insulator Material:

Contact Material:

Contact Material:

BeCu

Plating:
Au or Sn over
50µ" (1,27 µm) Ni
Current Rating (HLE/TSM):
4.1 A per pin
(1 pin powered per row)

4.1 A per pin (1 pin powered per row) Voltage Rating: 400 VAC Operating Temp Range:

-55°C to +125°C
Insertion Depth:
(1,78 mm) .070" to
(3,43 mm) .135", pass-through,
or (2,59 mm) .102" min
plus board thickness for
bottom entry
Insertion Force:

(Single contact only) 2 oz (0,56 N) avg. Withdrawal Force: (Single contact only) 1.6 oz (0,44 N) avg. RoHS Compliant:

Processing: Lead-Free Solderable:

SMT Lead Coplanarity: (0,10 mm) .004" max (02-20) (0,15 mm) .006" max (21-50)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality





ALSO AVAILABLE (MOQ Required)

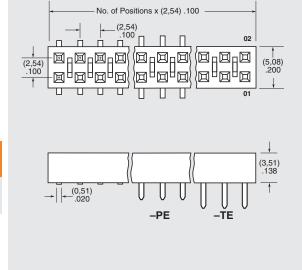
Other platings
 Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.



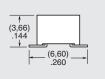
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

02 thru 50



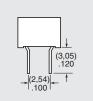
Leave blank for Surface Mount

OPTION

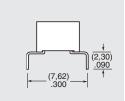


(Requires –BE for Bottom Entry)

−TE =Through-Hole Top Entry



PE
= Through-hole
Pass-Through Entry



(Requires –BE for Bottom Entry)

OPTION

OTHER

-BE = Bottom Entry (N/A with -TE)

-A = Alignment Pin (4 positions min.) Metal or plastic at Samtec discretion (N/A with -TE, -PE & -LC)



-LC = Locking Clip (2 positions min.) (N/A with -A) (Manual placement



required)

1,42) 056 - K

= (6,50 mm) .256"
DIA Polyimide
Film Pick &
Place Pad
(3 positions min.)
Not available
with -TE or
-PE tail option

– P = Metal Pick & Place Pad (3 positions <u>min.)</u>



-TR = Tape & Reel Packaging (29 positions max.)